ABSTRACT

A heating and pressurizing apparatus (101), to which a circuit board (70) with electronic components (8) pre-bonded thereto via bonding elements (9) is carried in, is provided. The heating and pressurizing apparatus post-bonds the electronic component to the circuit board by heating and pressurizing the electronic component by a contact member (1211) having a heating device (122). By executing the pre-bonding and the post-bonding of the electronic components to the circuit board independently of each other, the time required for the post-bonding can be reduced, compared with the conventional case, and the productivity of the whole mounting line can be improved.